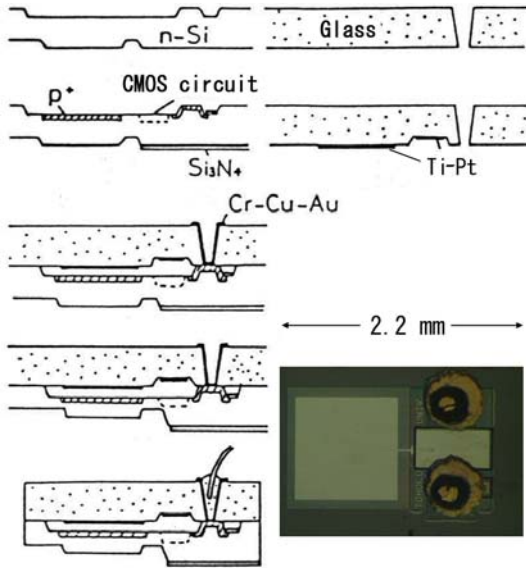
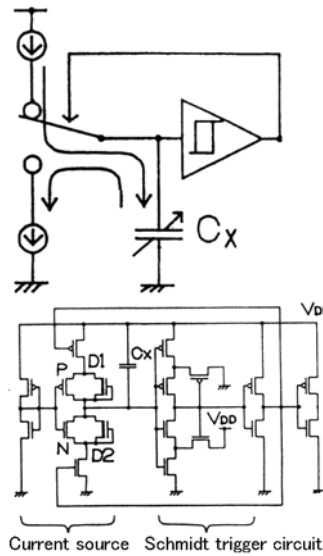


Integrated Capacitive Pressure Sensor

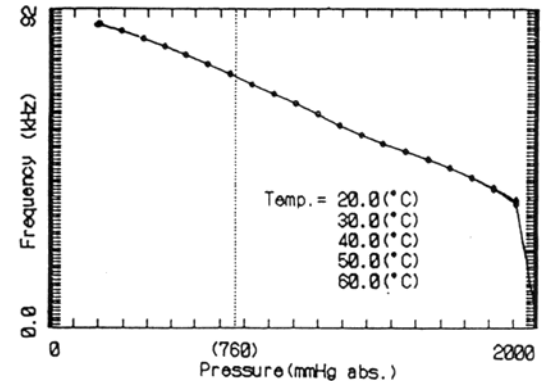
(Tohoku Univ. — Toyda Machine Works)



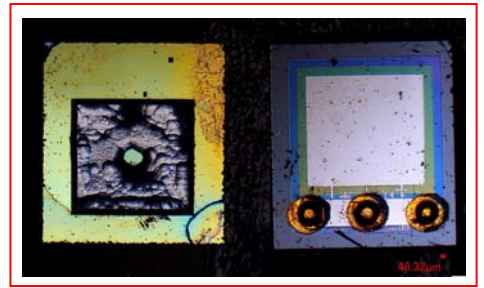
Fabrication process



Circuit



Characteristics



For low pressure measurement

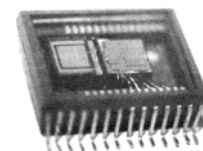
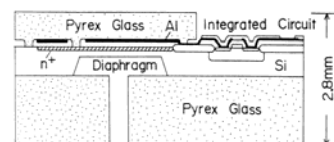
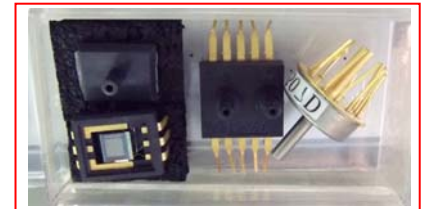
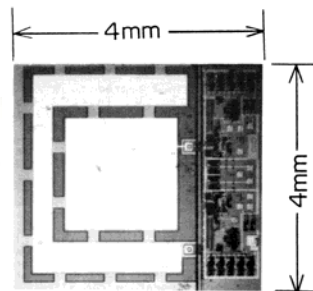
10mmH₂O~300mmH₂O

Frequency and analog output

TOYODA

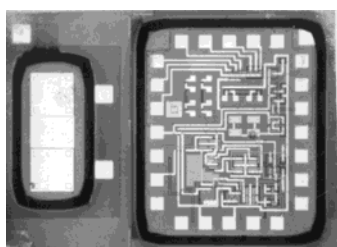
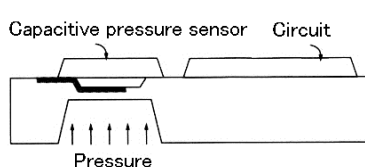
Toyoda Machine Works, LTD.

Monolithic capacitive pressure sensor



Reference : Y.Matsumoto, S.Shoji and M.Esashi, A Miniature Integrated Capacitive Pressure Sensor, Extended Abstracts of the 22nd International Conference on Solid State Devices and Materials (1990) pp.701-704

Integrated Capacitive Pressure Sensor by Si Direct Bonding

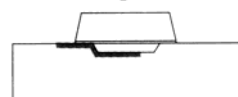


Structure and photograph

1) Direct bonding



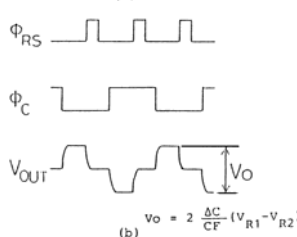
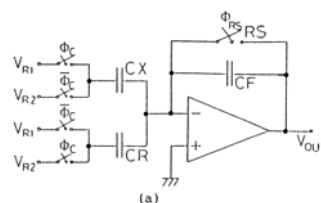
2) Si etching



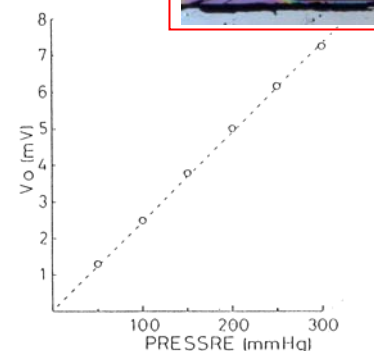
3) Si etching for diaphragm



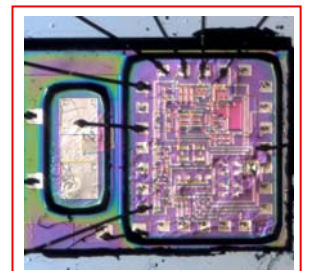
Fabrication



Circuit



Characteristics



Reference : S.Shoji, T.Nisase, M.Esashi and T.Matsuo, Fabrication of an Implantable Capacitive Type Pressure Sensor, The 4th Int. Conf. on Solid State Sensors and Actuators (transducers' 87), (1987) pp.305-308